IPC ASSOCIATION ELECTRONIC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.					This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Form Type Distribute				Form Type * Distribute	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					als and M	g Informa	ation		
Supplier	· Information														
Company name*				Company unique ID			Unique ID Authority					Response Date*			
nsemi												2024-04-30			
Contact N	ame		Title - Contact				Phone - Contact*					Email - Contact*			
Product-I	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorize	d Representative*		Title - Representative				Phone - Representative*				Email - Representative*				
Product-I	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item N		Number Mfr Item Name				Effective Da	ite V	ersion	Manufacturing Site		1	Veight*	UOM	Unit Type
		LC87F2708AUMD- AH 8-bit Microco		8-bit Microcontro	roller		2024-04-30					1	30.0	mg	Each
//////////////////////////////////////	cturing Proccess Information	on													
	Terminal Plating / Grid Array Material		Cerminal Base Alloy J-STD-02		J-STD-020 MSL	Rating	Peak Process Body T		Body Temperatu	mperature Max Time at Peak		Temperature Number		nber of Reflow Cyc	eles
	contains Bi		CU Alloy 4		1		260 C		С	30 seco		secon	is 3		
omments															
or more i	information regarding material co	omposition j	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's sliability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale app											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.5	mg	Supplier	Silicon (Si)	7440-21-3		2.4845	mg
			Supplier	Polyimide	Proprietary Data		0.0155	mg
Die Attach	0.24	mg	Supplier	Silver (Ag)	7440-22-4		0.1836	mg
			Supplier	Epoxy resins	129915-35-1		0.0564	mg
Lead Frame	16.07	mg	Supplier	Silver (Ag)	7440-22-4		0.6717	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0305	mg
			Supplier	Iron (Fe)	7439-89-6		0.4001	mg
			Supplier	Copper (Cu)	7440-50-8		14.9451	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0225	mg
Mold Compound-Black	109.14	mg		Epoxy Phenol Resin	proprietary data		12.0054	mg
			Supplier	Carbon Black (C)	1333-86-4		0.5457	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		49.6587	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		46.9302	mg
Plating	1.72	mg	В	Bismuth (Bi)	7440-69-9		0.0103	mg
			Supplier	Tin (Sn)	7440-31-5		1.7097	mg
Wire Bond - Au	0.33	mg	Supplier	Gold (Au)	7440-57-5		0.33	mg